

L Number	Hits	Search Text	DB	Time stamp
1	6	("5566262" "5727105" "5613031" "3845260" "3721948").pn.	USPAT; US-PGPUB; EPO; JPO	2003/08/08 15:55
2	8	("5778125" "5598496" "6282349" "3987300" "5866263" "5641713" "5157753" "5250843").pn.	USPAT; US-PGPUB; EPO; JPO	2003/08/08 16:15
-	8576	385/94.ccls. 257/99,100,433,729,787-796.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/02 17:07
-	8579	385/94.ccls. 257/99,100,433,729,787-796.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/02 17:07
-	823	(385/94.ccls. 257/99,100,433,729,787-796.ccls.) and (hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight") and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 13:43
-	4298	(385/94.ccls. 257/99,100,433,729,787-796.ccls.) and (sealed seal\$6) and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 13:44
-	1273	(385/94.ccls. 257/99,100,433,729,787-796.ccls.) and ((sealed seal\$6) near6 (container environment packag\$4 contained capusule contain\$4 encapulat\$4)) and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 13:38
-	3430	(385/94.ccls. 257/99,100,433,729,787-796.ccls.) and (sealed sealingly seal) and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 11:19
-	292	385/94.ccls. and (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin)	USPAT; US-PGPUB; EPO; JPO	2003/08/08 10:35
-	823	(385/94.ccls. 257/99,100,433,729,787-796.ccls.) and (hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight") and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 16:50
-	139	(385/94.ccls. and (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin)) not ((385/94.ccls. 257/99,100,433,729,787-796.ccls.) and (hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight") and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck))	USPAT; US-PGPUB; EPO; JPO	2003/08/04 13:46
-	4	("4221461" "4265699" "4290667" "4812002").PN.	USPAT	2003/08/04 14:38
-	338	(439/271-277.ccls. 200/302.1.ccls.) and (hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight") and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 solder\$4 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 16:52
-	363	(439/271-277.ccls. 200/302.1.ccls.) and (hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant") and (bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 solder\$4 stick sticking stuck)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 17:20
-	7	3845260.URPN.	USPAT	2003/08/04 19:06
-	2	("2381582" "3711668").PN.	USPAT	2003/08/04 19:09
-	9391	257/433,684,678,687,701-703,708,729,787-796.ccls. and (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin)	USPAT; US-PGPUB; EPO; JPO	2003/08/04 19:29

1205	257/433,684,678,687,701-703,708,729,787-796.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))	USPAT; US-PGPUB; EPO; JPO	2003/08/04 19:39
840	257/433,684,678,687,701-703,708,729.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))	USPAT; US-PGPUB; EPO; JPO	2003/08/04 19:44
546	257/790.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/04 19:44
12	5208467.URPN.	USPAT	2003/08/04 19:55
10	("3644801" "4001872" "4024570" "4486945" "4723197" "4777520" "4788583" "4845543" "4866506" "5057900").PN.	USPAT	2003/08/04 19:55
10	("3644801" "4001872" "4024570" "4486945" "4723197" "4777520" "4788583" "4845543" "4866506" "5057900").PN.	USPAT	2003/08/04 19:55
828	257/433,684,678,687,701-703,708,729.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4)) not 257/790.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:22
60	156/325-338.ccls. and (electr\$6 current wire) and (hermet\$8)	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:24
0	156/325-338.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:23
193	156/325-338.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:37

-	168	(156/325-338.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))) and (packag\$4 contain\$4 hous\$4 enclos\$4)	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:37
-	102	(156/325-338.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))) and (electr\$6 current wire)	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:34
-	72	439/935.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:36
-	299	439/935-936.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:37
-	352	439/933,935-936.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:37
-	78	439/933,935-936.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4)))	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:38
-	70	(439/933,935-936.ccls. and ((hermetic\$5 air-tight water-tight airtight watertight "air tight" "water tight" "water resistant" "chemical resistance" "chemically resistant" "gas tight" "prevent gas" "prevent water" "prevent air") same (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin epox\$4))) and (packag\$4 contain\$4 hous\$4 enclos\$4)	USPAT; US-PGPUB; EPO; JPO	2003/08/07 17:58
-	6	"071141"	USPAT; US-PGPUB; EPO; JPO	2003/08/08 10:31
-	984	385/116.ccls.	USPAT; US-PGPUB; EPO; JPO	2003/08/08 10:35
-	583	385/116.ccls. and (adhesive bond\$4 glue\$4 seal\$4 affix\$4 adher\$5 stick sticking stuck solder\$4 Ni cd chromium copper cu cr au gold tungsten titanium ti nickel ni aluminum al "silicon oxide" "silicon nitride" sin)	USPAT; US-PGPUB; EPO; JPO	2003/08/08 15:52